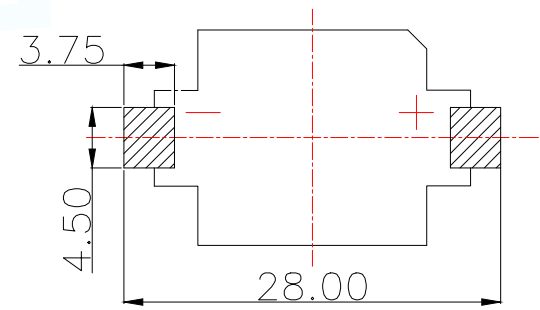
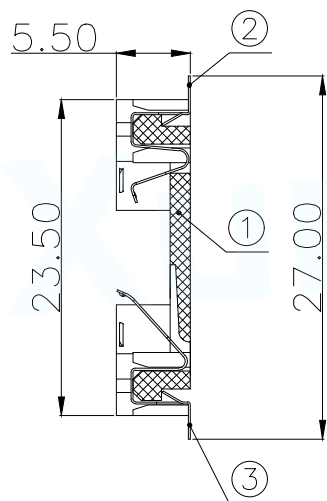
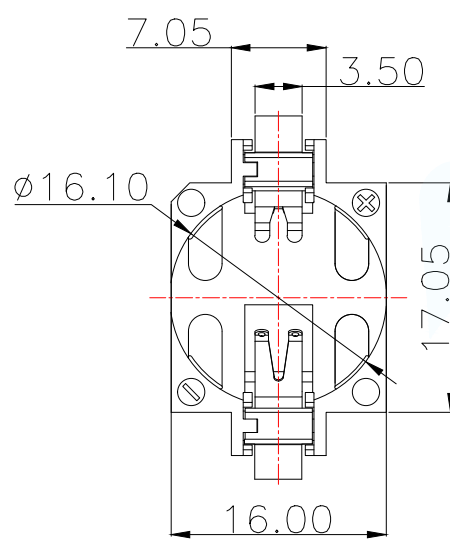




| | | | |
|------|--------------|------|------|
| 12 | 13 | 14 | 15 |
| MAPX | MODIFICATION | DATE | DRAW |
| | | | |

NOTE:
 1.MATERIAL:
 a.HOUSING:LCP UL94V-0
 b.CONTACT:PHOSPHOR BRONZE
 (SURFACE PLATING: Au 1U")
 2.ELECTRIC:
 a.CONTACT RESISTANCE: 30 MILLIOHMS
 MAX
 b.INSULATION RESISTANCE: 100 MEGA
 OHMS MIN
 c.DIELECTNIC VOLTAGE: 500V AC ONE
 SEC LEVEL
 d.OPERATING TEMPERATURE: -25°C~
 +85°C



PCB Layout Diagram
Top View

| | | | | |
|-----|-------------|------|---------------------------|-----------------|
| 3 | TERMINAL(-) | 1 | PHOSPHOR BRONZE, T=0.15mm | Au-Plating |
| 2 | TERMINAL(+) | 1 | PHOSPHOR BRONZE, T=0.15mm | Au-Plating |
| 1 | HOUSING | 1 | LCP | WHITE |
| NO. | PART NAME | Q'TY | MATERIAL | PLATING & COLOR |

| | | | | |
|---------------------------------------|---------|---|------------------|---------------|
| MANUFACTURE DWG | | 东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co.,Ltd | | |
| UNLESS OTHERWISE SPECIFIED TOLERANCES | | | TITLE: Au SMT | |
| DECIMALS: | ANGLES: | | PAR | BS-1601-SA-4W |
| X.X±0.30 | X.*±5' | | DWN | |
| X.XX±0.25 | X.X'±1' | | CHKD | |
| X.XXX±0.15 | | APVD | | |
| CUSTOMER COPY | | SCALE N:A | UNIT:MM | |
| | | SIZE:A4 | SHEET:1F1 | |
| | | | REV:A | |